

# Schottky

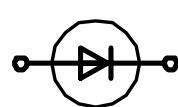
# High Performance Schottky Diode

## Low Loss and Soft Recovery

### Single Diode

$$\begin{aligned}V_{RRM} &= 100 \text{ V} \\I_{FAV} &= 1 \text{ A} \\V_E &= 0.65 \text{ V}\end{aligned}$$

**Part number** (Marking on product)  
**DSA 1 I 100 SA** (**S1KA**)



## **Features / Advantages:**

- Very low Vf
  - Extremely low switching losses
  - Low  $I_{rm}$ -values
  - Improved thermal behaviour
  - High reliability circuit operation
  - Low voltage peaks for reduced protection circuits
  - Low noise switching
  - Low losses

### **Applications:**

- Rectifiers in switch mode power supplies (SMPS)
  - Free wheeling diode in low voltage converters
  - Decoupling diode

## Package:

- Industry standard outline
  - Epoxy meets UL 94V-0
  - RoHS compliant

## Ratings

Symbol	Definition	Conditions	min.	typ.	max.	Unit
$V_{RRM}$	max. repetitive reverse voltage	$T_{VJ} = 25^\circ C$			100	V
$I_R$	reverse current	$V_R = 100 V$	$T_{VJ} = 25^\circ C$		0.01	mA
		$V_R = 100 V$	$T_{VJ} = 125^\circ C$		5	mA
$V_F$	forward voltage	$I_F = 1 A$	$T_{VJ} = 25^\circ C$		0.79	V
		$I_F = 2 A$			0.87	V
	forward voltage	$I_F = 1 A$	$T_{VJ} = 125^\circ C$		0.65	V
		$I_F = 2 A$			0.75	V
$I_{FAV}$	average forward current	rectangular, $d = 0.5$	$T_L = 125^\circ C$		1	A
$V_{F0}$ $r_F$	threshold voltage slope resistance } for power loss calculation only		$T_L = 175^\circ C$			V mΩ
$R_{thJL}$	thermal resistance junction to lead*				40	K/W
$T_{VJ}$	virtual junction temperature		-55		175	°C
$P_{tot}$	total power dissipation	$T_L = 25^\circ C$			3	W
$I_{FSM}$	max. forward surge current	$t_p = 10 ms$ (50 Hz), sine	$T_{VJ} = 45^\circ C$		45	A
$C_J$	junction capacitance	$V_R = 5 V$ ; $f = 1 MHz$	$T_{VJ} = 25^\circ C$		45	pF
$E_{AS}$	non-repetitive avalanche energy	$I_{AS} = A$ ; $L = 100 \mu H$	$T_{VJ} = 25^\circ C$		tbd	mJ
$I_{AR}$	repetitive avalanche current	$V_A = 1.5 \cdot V_R$ typ.; $f = 10 kHz$			tbd	A

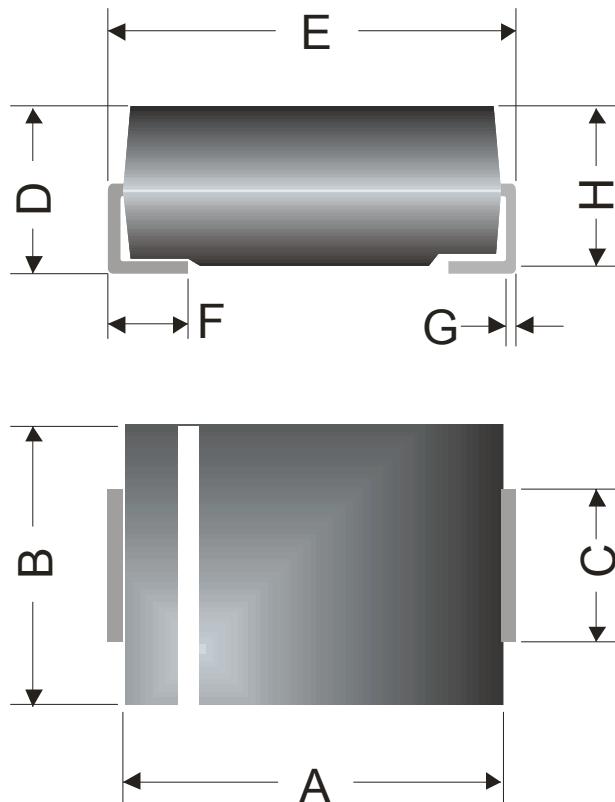
\* mounted on 1 inch square PCB

Symbol	Definition	Conditions	Ratings		
			min.	typ.	max.
$I_{RMS}$	RMS current	per pin*			A
$R_{thJA}$	thermal resistance junction to ambient			80	K/W
$M_D$	mounting torque				Nm
$F_c$	mounting force with clip				N
$T_{stg}$	storage temperature		-55		150 °C
Weight				0.07	g

\*  $I_{RMS}$  is typically limited by: 1. pin-to-chip resistance; or by 2. current capability of the chip.

In case of 1, a common cathode/anode configuration and a non-isolated backside, the whole current capability can be used by connecting the backside.

### Outlines SMA (DO-214AC)



Dim.	Millimeters		Inches	
	min	max	min	max
A	3.99	4.50	0.157	0.177
B	2.54	2.79	0.100	0.110
C	1.25	1.65	0.049	0.065
D	1.98	2.29	0.078	0.090
E	4.93	5.28	0.194	0.208
F	0.76	1.52	0.030	0.060
G	0.15	0.31	0.006	0.012
H	2.00	2.20	0.079	0.087